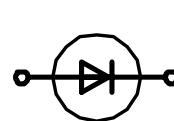


Schottky

High Performance Schottky Diode
Low Loss and Soft Recovery
Single Diode

V_{RRM} = 40 V
I_{FAV} = 1 A
V_F = 0.40 V

Part number (Marking on product)
DSB 1 I 40 SA (**S1FB**)

**Features / Advantages:**

- Very low V_f
- Extremely low switching losses
- Low I_{rm}-values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters
- Decoupling diode

Package:

- SMA (DO-214AC)
 - Industry standard outline
 - Epoxy meets UL 94V-0
 - RoHS compliant

Ratings						
Symbol	Definition	Conditions	min.	typ.	max.	Unit
V _{RRM}	max. repetitive reverse voltage	T _{vj} = 25 °C			40	V
I _R	reverse current	V _R = 40 V T _{vj} = 25 °C V _R = 40 V T _{vj} = 125 °C			0.1 15	mA
V _F	forward voltage	I _F = 1 A T _{vj} = 25 °C I _F = 2 A			0.48 0.58	V
		I _F = 1 A T _{vj} = 125 °C I _F = 2 A			0.40 0.50	V
I _{FAV}	average forward current	rectangular, d = 0.5 T _L = 125 °C			1	A
V _{F0} r _F	threshold voltage slope resistance } for power loss calculation only					V mΩ
R _{thJL}	thermal resistance junction to lead*				40	K/W
T _{vj}	virtual junction temperature		-55		150	°C
P _{tot}	total power dissipation	T _L = 25 °C			3	W
I _{FSM}	max. forward surge current	t _p = 10 ms (50 Hz), sine T _{vj} = 45 °C			45	A
C _J	junction capacitance	V _R = V; f = 1 MHz T _{vj} = 25 °C			78	pF
E _{AS}	non-repetitive avalanche energy	I _{AS} = A; L = 100 µH T _{vj} = 25 °C			tbd	mJ
I _{AR}	repetitive avalanche current	V _A = 1.5 · V _R typ.; f = 10 kHz			tbd	A

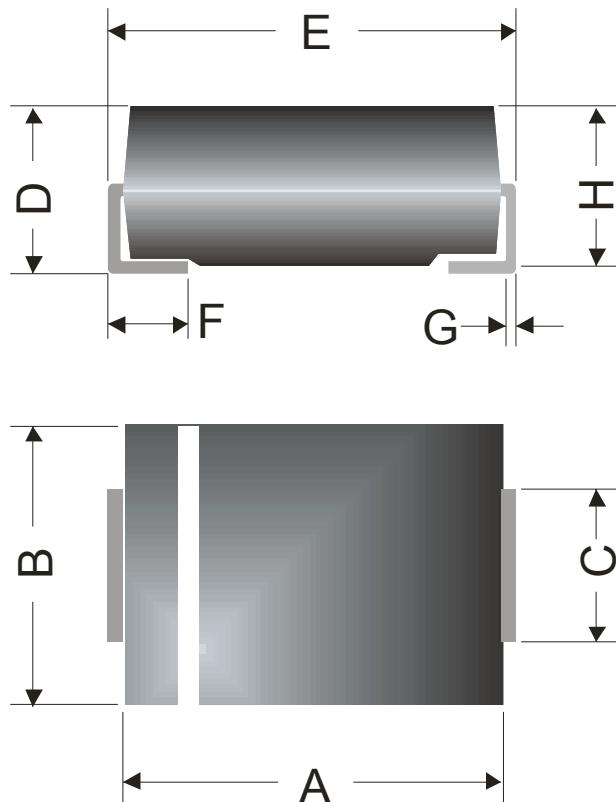
* mounted on 1 inch square PCB

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
I_{RMS}	RMS current	per pin*			A
R_{thJA}	thermal resistance junction to ambient			80	K/W
M_D	mounting torque				Nm
F_c	mounting force with clip				N
T_{stg}	storage temperature		-55		150 °C
Weight				0.07	g

* I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

Outlines SMA (DO-214AC)



Dim.	Millimeters		Inches	
	min	max	min	max
A	3.99	4.50	0.157	0.177
B	2.54	2.79	0.100	0.110
C	1.25	1.65	0.049	0.065
D	1.98	2.29	0.078	0.090
E	4.93	5.28	0.194	0.208
F	0.76	1.52	0.030	0.060
G	0.15	0.31	0.006	0.012
H	2.00	2.20	0.079	0.087